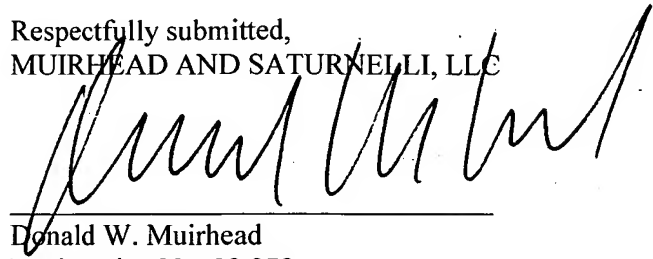


Should there be any questions after reviewing this paper, the Examiner is invited to contact the undersigned at (508) 898-8603.

Respectfully submitted,
MUIRHEAD AND SATURNELLI, LLC

A handwritten signature in black ink, appearing to read 'Donald W. Muirhead', is written over a horizontal line.

Date: January 22, 2008

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Claims 1 through 14

Cited Reference 1, Cited Reference 2, and Cited Reference 3

Remarks:

See [Figure 1] and related portions thereof in Cited Reference 1.

It is recognized that including a Ti layer or TiN layer in the invention described in Cited Reference 1 is something that could be appropriately devised by any person skilled in the art based on the description of Cited Reference 2 ([Figure 9] and related portions thereof).

Furthermore, it is recognized that the use of a layer in which the upper portion of the wiring layer is modified in the invention described in Cited Reference 1 is something that could be appropriately devised by any person skilled in the art based on the description of Cited Reference 3 (paragraph [0020]).

Table of Cited References, etc.

1. Japanese Patent Application Kokai No. 2001-257226
2. Japanese Patent Application Kokai No. 2000-100847
3. Japanese Patent Application Kokai No. 2000-315688